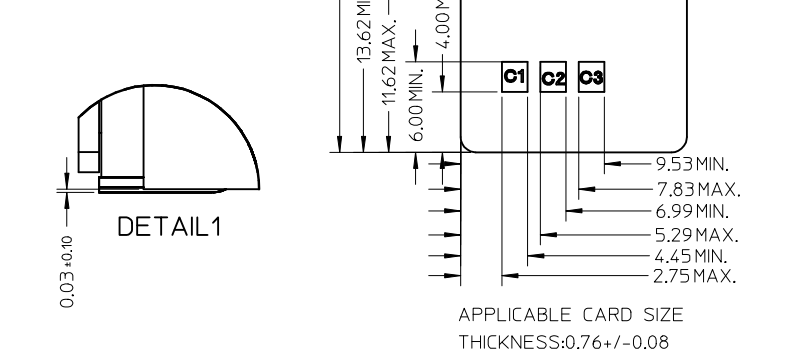
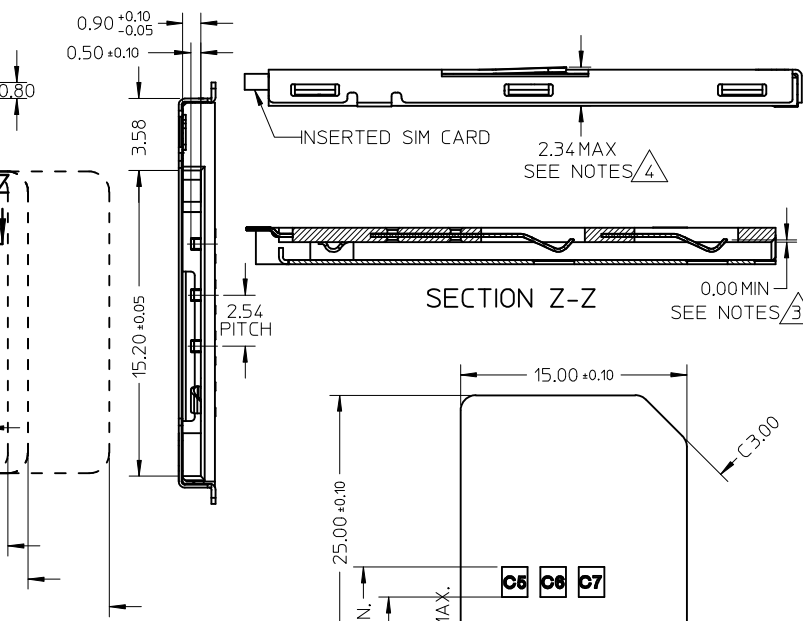
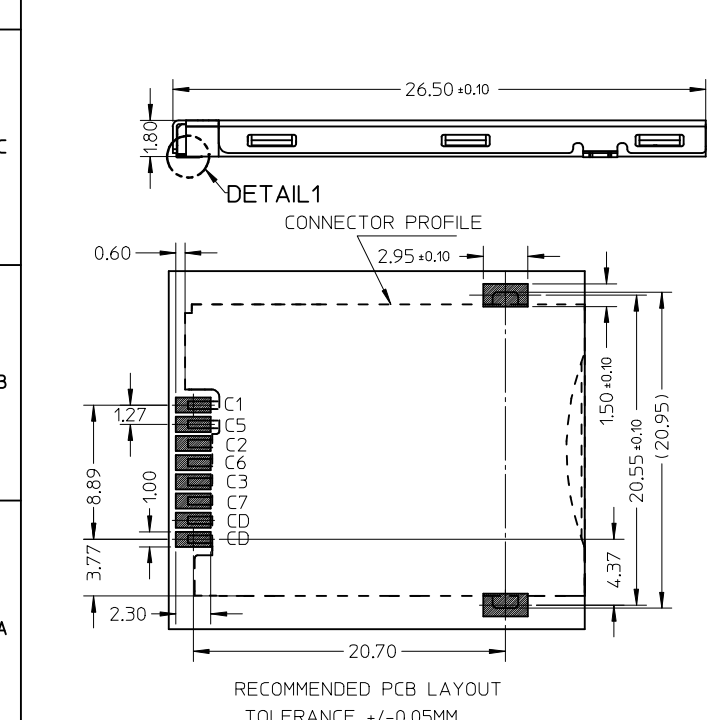
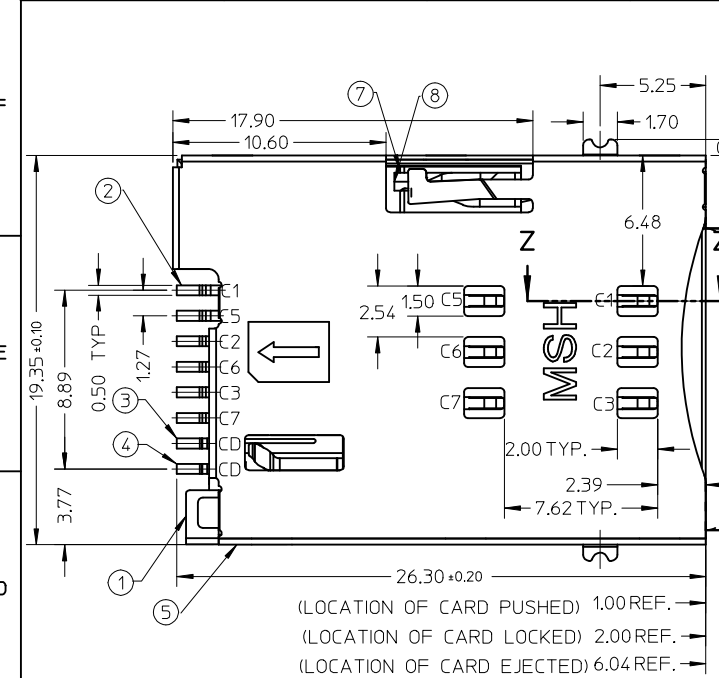


- NOTES
- FINISH
 - 1-1 TERMINAL :
50~200μ NICKEL UNDER PLATED
15μ MIN GOLD PLATING ON CONTACT AREA
3μ MIN GOLD FLASH ON SOLDERING AREA
 - 1-2 SHELL :
50~200μ NICKEL UNDER PLATED
3μ MIN GOLD FLASH ON SOLDERING AREA
 - 1-3 DETECT PIN :
50~200μ NICKEL UNDER PLATED
3μ MIN GOLD PLATING ON CONTACT AREA
3μ MIN GOLD FLASH ON SOLDERING AREA
 - DETECT SWITCH: INSERT CARD=ON (NORMAL=OPEN)
 - I.E., TERMINAL TIP WILL SINK INTO HOUSING.
 - SPRING RISE UP DURING PUSH-PUSH PERIOD
 - PRODUCT COMPLIANT TO ROHS DIRECTIVE 2011/65/EU AND ELV DIRECTIVE 2000/53/EC
 - SOLDERTAIL(10X) COPLANARITY 0.10MM MAX (BEFORE REFLOW)
 - PRODUCT SPECIFICATION: PS-47553-201
 - PACKAGE DRAWING: PK-47553-001

NO.	DESCRIPTION	Q'TY	MATERIAL
1	HOUSING	1	HIGH TEMPERATURE THERMOPLASTIC
2	TERMINAL	6	COPPER ALLOY
3	DETECT PIN LOWER	1	COPPER ALLOY
4	DETECT PIN UPPER	1	COPPER ALLOY
5	SHELL	1	STAINLESS STEEL
6	COIL SPRING	1	PIANO WIRE
7	HEART CAM	1	HIGH TEMPERATURE THERMOPLASTIC
8	CAM PIN	1	STAINLESS STEEL

COPLANARITY ADDED EC NO: S2013-0560 DRW:NEANG 2013/02/15 CHKD:JTAN02 2013/03/25 APPR:KHLIM 2013/03/25 G2	QUALITY SYMBOLS F=0 F=0 F=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES	±	---	---	DRAWN BY	DATE	TITLE PUSH PUSH 6 PINS SIM CONN. WITH DETECT PIN SALES DRAWING MOLEX MOLEX INCORPORATED DOCUMENT NO. SD-47553-001 SHEET NO. 1 OF 1		
		3 PLACES	±	---	---	CHECKED BY	DATE			
		2 PLACES	±	0.15	---	XU XIANG	2007/04/16			
1 PLACE	±	---	---	APPROVED BY	DATE					
ANGULAR ±---°				MATERIAL NO. 475530001		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				



- NOTES
- FINISH
 - 1-1 TERMINAL :
50~200μ NICKEL UNDER PLATED
15μ MIN GOLD PLATING ON CONTACT AREA
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 - SOLDERTAIL(10X) COPLANARITY 0.10MM MAX (BEFORE REFLOW)
 - PRODUCT SPECIFICATION: PS-47553-201
 - PACKAGE DRAWING: PK-47553-001

		CARD INSERTED		WITHOUT CARD	
NO.	DESCRIPTION	Q'TY	MATERIAL	NO.	DESCRIPTION
1	HOUSING	1	HIGH TEMPERATURE THERMOPLASTIC		
2	TERMINAL	6	COPPER ALLOY		
3	DETECT PIN LOWER	1	COPPER ALLOY		
4	DETECT PIN UPPER	1	COPPER ALLOY		
5	SHELL	1	STAINLESS STEEL		
6	COIL SPRING	1	PIANO WIRE		
7	HEART CAM	1	HIGH TEMPERATURE THERMOPLASTIC		
8	CAM PIN	1	STAINLESS STEEL		

COPLANARITY ADDED EC NO: S2013-0560 DRW:NEANG 2013/02/15 CHKD:JTAN02 2013/03/25 APPR:KHLIM 2013/03/25	QUALITY SYMBOLS F=0 F=0 F=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.15 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY LHSHEEN	DATE 2006/09/07	TITLE PUSH PUSH 6 PINS SIM CONN. WITH DETECT PIN SALES DRAWING					
		ANGULAR ± ---°		CHECKED BY XUXIANG	DATE 2007/04/16	MOLEX INCORPORATED					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY JENNYCHEN	DATE 2007/04/16	MATERIAL NO. 475530001		DOCUMENT NO. SD-47553-001	SHEET NO. 1 OF 1		